



Drill Map:

- × 2.921mm / 0.1150" (2 holes) (not plated)
- 3.200mm / 0.1260" (0 holes + 4 slots) (not plated)
- + 4.953mm / 0.1950" (2 holes) (not plated)
- 5.029mm / 0.1980" (1 hole) (not plated)
- ◇ 6.401mm / 0.2520" (12 holes) (not plated)
- ⊗ 7.214mm / 0.2840" (8 holes) (not plated)

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Black	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	White	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	Al	1.51 mm	Aluminum	8.7	0.001
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	White	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Black	1	0

NOTE: STACKUP TABLE IS FOR REFERENCE.
B.CU LAYER IS NOT NEEDED
FABRICATOR MAY ADJUST LAYER THICKNESS TO CONFORM WITH STANDARD STACKUP.
FABRICATOR MAY MAKE OUT OF 1.6MM ALUMINUM

BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm
Board overall dimensions: 71.1200 mm x 128.5240 mm
Min track/spacing: 0.0000 mm / 0.0000 mm Min hole diameter: 0.3000 mm
Copper Finish: Not specified Impedance Control: No
Castellated pads: No Plated Board Edge: No
Edge card connectors: No

NOTE: PCB MUST CONFORM WITH THE ROHS DIRECTIVE OF THE EUROPEAN UNION

Black and White Fabrication – Page 1/1

Dialtone Synthesis

Sheet: Black and White Fabrication
File: 201_Blank_Faceplate.kicad_pcb

Title: 200 Series Blank Faceplate

Size: A4 Date: 2025-03-18 Rev: A1

KiCad E.D.A. 9.0.0 Id: /1